Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.052”**

**ANODE**

**.047 x .047”**

**.052”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size = .047 x .047”**

**Backside Potential: CATHODE**

**Mask Ref: CP108**

**APPROVED BY: DK DIE SIZE .052” X .052 DATE: 9/2/21**

**MFG: CENTRAL SEMI THICKNESS .009” P/N: 1N5819**

**DG 10.1.2**

#### Rev B, 7/1